

Title (en)

BONDING AGENT HARDENABLE BY HIGH-ENERGY RADIATION AND/OR THERMALLY

Title (de)

MIT ENERGIEREICHER STRAHLUNG UND/ODER THERMISCH HÄRTBARE BINDEMITELE

Title (fr)

LIANT DURCISSABLE PAR UN RAYONNEMENT HAUTE ENERGIE ET/OU PAR LA CHALEUR

Publication

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Application

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Abstract (en)

[origin: DE19835917A1] The invention relates to a bonding agent, preferably for a lacquer, which may be hardened by high-energy radiation and/or thermally and which contains a mixture of substances (a) having a monomer or polymer component including at least one vinyl ether, vinyl ester, (meth)acrylic and/or allyl group, and (b) containing saturated and/or unsaturated polymers different from component (a) as additional component, with the proviso that at least one of components (a), (b) contains structural units of general formulae (I) and/or (II) and the additional component (b) contains structural units of general formulae (I) and/or (II) at least when said component contains saturated polymers. The invention also relates to a method for the production of the bonding agent and a preparation containing the bonding agent according to the invention. Said preparation is obtained in the form of a pigmented or non-pigmented lacquer or a powder lacquer. The invention also relates to a working method for the production of lacquer coatings, wherein after application, said coatings are hardened thermally and/or by radiation with UV light or electron beams.

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